

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **2001345548 A**

(43) Date of publication of application: **14.12.01**

(51) Int. Cl.

H05K 3/34
B23K 1/00
B23K 1/008
B23K 31/02
// B23K101:42

(21) Application number: **2000162202**

(22) Date of filing: **31.05.00**

(71) Applicant: **FUJI ELECTRIC CO LTD**

(72) Inventor: **IKEMI KAZUHISA**
OKAMOTO KOKICHI

(54) METHOD OF JOINTING INSERTED AND MOUNTED PARTS BY REFLOW SOLDER

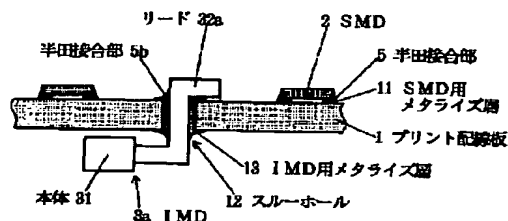
(57) Abstract:

PROBLEM TO BE SOLVED: To provide a reflow-soldering method for an IMD, which can mount the IMD at the same time with an SMD on a printed wiring board, without impairing the performance of the IMD.

SOLUTION: The lands at the tops of a metallized layer (pad) 11 for SMD at the top of a printed wiring board 1 and a metallized layer 13 for an IMD are supplied with paste solder, and the lead 32a of the IMD 3a is inserted into a through-hole 12 from the downside of the printed wiring board 1, and the tip is bent at right angle to hold the IMD 3a, and an SMD 2 is mounted on the pad 11. In this condition, it is heat-treated in a heat treating furnace, where the temperature on the side of the top is heated to a solder junction temperature and the temperature on the side of the bottom is kept at or lower than the heat resistant temperature of a body 31 of the IMD 3a. Thus, a solder junction parts

5 and 5b are formed of paste solder, and the IMD 3a and the SMD 2 are mounted on the printed wiring board 1.

COPYRIGHT: (C)2001,JPO



BEST AVAILABLE COPY